

# SOT858-2

plastic thermal enhanced low profile land grid array package;  
68 lands; resin based; body 10 x 15 x 1.25 mm

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	HLLGA68R
<b>Package type industry code</b>	HLLGA68R
<b>Package style descriptive code</b>	HLLGA (thermal enhanced low profile land grid array)
<b>Package style suffix code</b>	R (resin based)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	15-11-2007

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		9.9	-	10	10.1	mm
E	package width		14.9	-	15	15.1	mm
A	seated height		[tbd]	-	1.25	1.3	mm
A <sub>2</sub>	package height		[tbd]	-	1.25	[tbd]	mm
n <sub>2</sub>	actual quantity of termination		-	-	68	-	



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2. Package outline

HLLGA68R: plastic thermal enhanced low profile land grid array package;  
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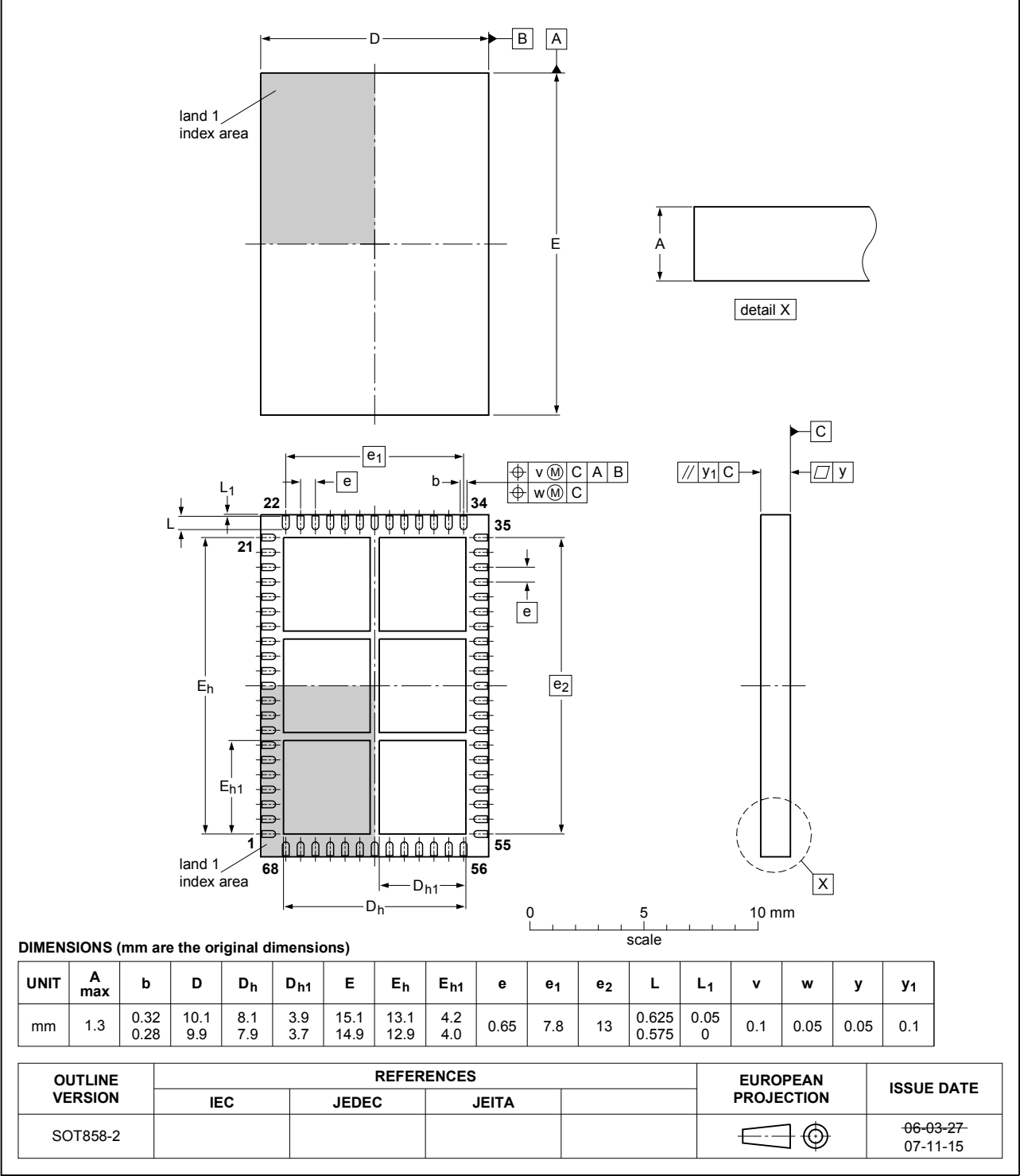
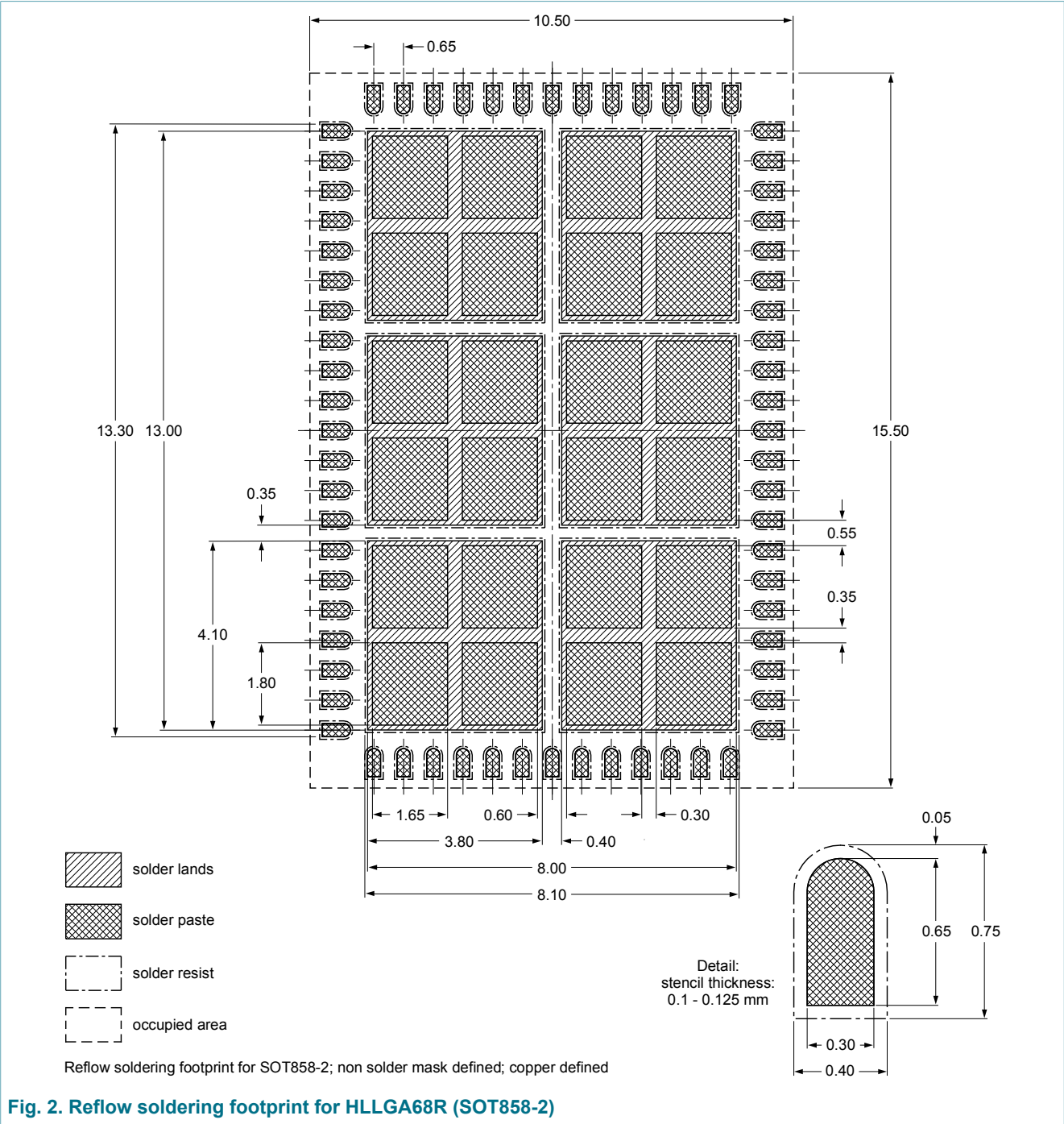


Fig. 1. Package outline HLLGA68R (SOT858-2)

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3. Soldering



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## 4. Legal information

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Date of release: 8 February 2016